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# PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of Gedney et al.	)	
	)	
Serial No:	To be assigned	)
		)
Filed:	Herewith	)
		)
For:	IC CHIP ATTACHMENT	)
		)
Reissue of U.S. Patent No. 5,483,421		)
		)
Issued:	January 9, 1996	)

Art Unit: Unknown
Examiner: Unknown
Attorney's Docket No:
EN9-91-022R
(21325/00276)

PRELIMINARY AMENDMENT

Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Sir:

Please amend page 7, lines 7-18 of the specification for the reissue application submitted herewith as follows:

In the present invention, the chip carrier 24 preferably is made of the same material as the circuit board, as will be described presently. If the chip carrier is not fashioned from the same material as the board, it must, in any event, have a similar coefficient of thermal expansion; i.e. the difference in the coefficient of thermal expansion between the carrier and the circuit board should not vary more than about 20%. The chip carrier and board are made from an organic dielectric material. In the preferred embodiment, the chip carrier and the board are both made of the above noted glass filled epoxy FR-4 material [which has] [having] a thermal coefficient of expansion of [at least about]  $15 \times 10^{-6}$  ppm/°C, preferably at least about  $16 \times 10^{-6}$  ppm/°C, and even more preferably about  $17-20 \times 10^{-6}$  ppm/°C.